



28129  
1806

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kie Y. Ahn et al.

Title: SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION

Docket No.: 303.672US1  
Filed: January 18, 2000  
Examiner: Ha Nguyen  
Customer No.: 21186

Serial No.: 09/483881  
Due Date: N/A  
Group Art Unit: 2812  
Confirmation No.: 8976

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- A return postcard.
- An Supplemental Information Disclosure Statement (2 pgs.), Form 1449 (7 pgs.), and copies of 183 cited documents.
- A check in the amount of \$180.00 to cover the fee for consideration of Information Disclosure Statement under 97(c).

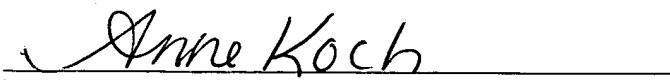
If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
Customer Number 21186

  
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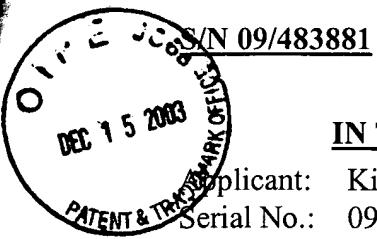
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SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A. Customer Number 21186  
(GENERAL)



PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Kie Y. Ahn et al. Examiner: Ha Nguyen  
Serial No.: 09/483881 Group Art Unit: 2812  
Filed: January 18, 2000 Docket: 303.672US1  
Title: SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION

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**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(2), Applicants have included the fee of \$180.00 as set forth in 37 C.F.R. §1.17(p). Please charge any additional fees or credit any overpayment to Deposit Account No. 19-0743.

12/17/2003 ZJUHAR1 00000044 09483881

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The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

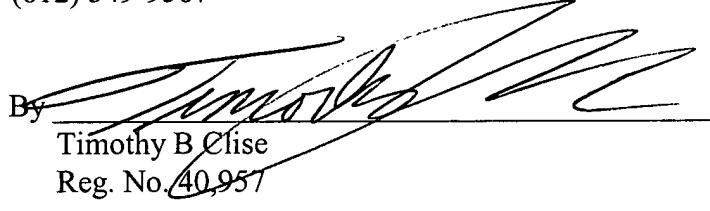
Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
P.O. Box 2938  
Minneapolis, MN 55402  
(612) 349-9587

Date 10 Dec '03

By   
Timothy B Clise  
Reg. No. 40,951

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Name

  
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**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**  
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Sheet 1 of 7

|                             |                  |
|-----------------------------|------------------|
| <i>Complete if Known</i>    |                  |
| <b>Application Number</b>   | 09/483881        |
| <b>Filing Date</b>          | January 18, 2000 |
| <b>First Named Inventor</b> | Ahn, Kie         |
| <b>Group Art Unit</b>       | 2812             |
| <b>Examiner Name</b>        | Nguyen, Ha       |

Attorney Docket No: 303.672US1

**US PATENT DOCUMENTS**

| Examiner Initial * | USP Document Number | Publication Date | Name of Patentee or Applicant of cited Document | Class | Subclass | Filing Date If Appropriate |
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EXAMINER

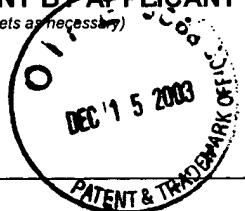
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| <b>Application Number</b>   | 09/483881        |
| <b>Filing Date</b>          | January 18, 2000 |
| <b>First Named Inventor</b> | Ahn, Kie         |
| <b>Group Art Unit</b>       | 2812             |
| <b>Examiner Name</b>        | Nguyen, Ha       |

Sheet 2 of 7

Attorney Docket No: 303.672US1

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|--|--------------|------------|--------------------------------|-----|-------|------------|
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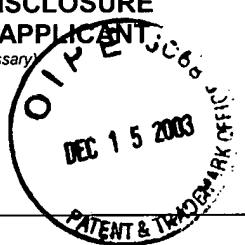
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Sheet 3 of 7

Attorney Docket No: 303.672US1

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EXAMINER

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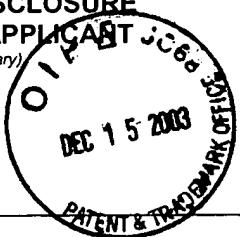
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| <b>Examiner Name</b>        | Nguyen, Ha       |

Sheet 4 of 7

Attorney Docket No: 303.672US1

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| US-6,091,475 | 07/18/2000 | Ogino, T. , et al.        | 349 | 149 | 12/09/1997 |
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| US-6,143,641 | 11/07/2000 | Kitch, Vassili            | 438 | 618 | 01/26/2000 |
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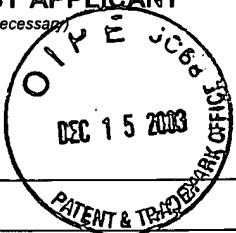
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Sheet 5 of 7

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| <b>Application Number</b>   | 09/483881        |
| <b>Filing Date</b>          | January 18, 2000 |
| <b>First Named Inventor</b> | Ahn, Kie         |
| <b>Group Art Unit</b>       | 2812             |
| <b>Examiner Name</b>        | Nguyen, Ha       |

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| Examiner Initials* | Foreign Document No | Publication Date | Name of Patentee or Applicant of cited Document | Class | Subclass | T <sup>2</sup> |
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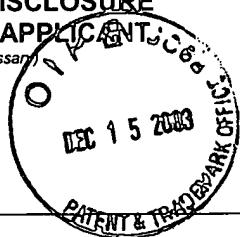
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| <b>Group Art Unit</b>       | 2812             |
| <b>Examiner Name</b>        | Nguyen, Ha       |

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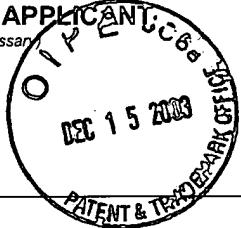
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